

Features

- Uses CRM(CQ) advanced SkyMOS1 technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Qualified according to JEDEC criteria

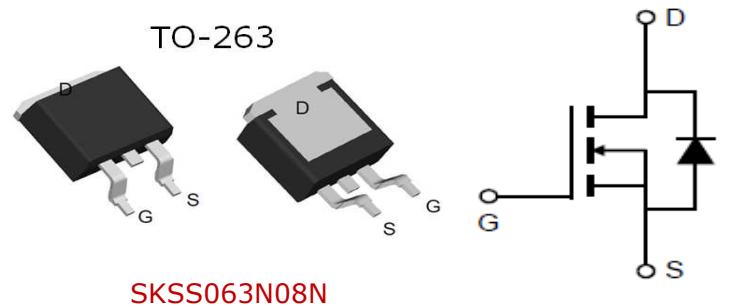
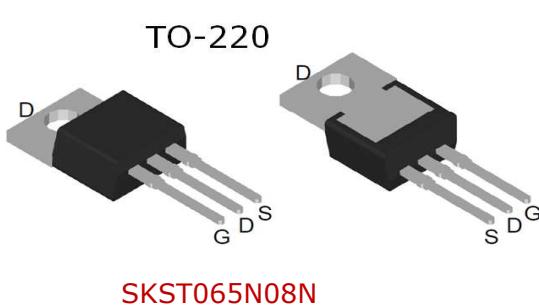
Product Summary

Wafer Code	WCB
VDS	85V
$R_{DS(on)}$	5.6mΩ
I_D	105A

Applications

- Motor control and drive
- Battery management
- UPS (Uninterruptible Power Supplies)

100% Avalanche Tested


Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
SKST065N08N	-	TO-220	Tube	N/A	N/A	50pcs
SKSS063N08N	-	TO-263	Tube	N/A	N/A	50pcs

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	85	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 25^\circ\text{C}$ (Package limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	I_D	121 120 70	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	I_D pulse	480	A
Avalanche energy, single pulse ($L=0.5\text{mH}$, $R_g=25\Omega$)	$E_{AS}(\text{Note 1})$	110	mJ
Gate-Source voltage	V_{GS}	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	164	W
Operating junction and storage temperature	T_j , T_{stg}	-55...+150	°C

 *. Notes:1.EAS is tested at starting $T_j = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $I_{AS} = 21\text{A}$, $V_{GS} = 10\text{V}$.

IAS(max)=42A;EAS(max)=441mJ under above Conditions;



Thermal Resistance

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R _{thJC}	0.76	°C/W
Thermal resistance, junction – ambient(min. footprint)	R _{thJA}	65	

Electrical Characteristic (at T_j = 25 °C, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV _{DSS}	85	97	-	V	V _{GS} =0V, I _D =250uA
Gate threshold voltage	V _{GS(th)}	2	3	4	V	V _{DS} =V _{GS} , I _D =250uA
Zero gate voltage drain current	I _{DSS}	-	0.05	1	μA	V _{DS} =80V, V _{GS} =0V T _j =25°C T _j =125°C
Gate-source leakage current	I _{GSS}	-	10	100	nA	V _{GS} =±20V, V _{DS} =0V
Drain-source on-state resistance	R _{DS(on)}	-	5.6	6.5	mΩ	V _{GS} =10V, I _D =50A TO-220
		-	5.4	6.3		TO-263
Transconductance	g _f	-	70	-	S	V _{DS} =5V, I _D =40A

Dynamic Characteristic

Input Capacitance	C _{iss}	-	2860	-	pF	V _{GS} =0V, V _{DS} =42.5V, f=1MHz
Output Capacitance	C _{oss}	-	790	-		
Reverse Transfer Capacitance	C _{rss}	-	19	-		
Gate Total Charge	Q _G	-	47	-	nC	V _{GS} =10V, V _{DS} =42.5V, I _D =50A, f=1MHz
Gate-Source charge	Q _{gs}	-	13	-		
Gate-Drain charge	Q _{gd}	-	11	-		
Turn-on delay time	t _{d(on)}	-	16	-		
Rise time	t _r	-	31	-		
Turn-off delay time	t _{d(off)}	-	36	-	ns	V _{ds} =42.5V Id=10A Rg=3.5Ω Vgs=10V; (Note 2,3)
Fall time	t _f	-	19	-		
Gate resistance	R _G	-	3.3	-	Ω	V _{GS} =0V, V _{DS} =0V, f=1MHz

Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V _{SD}	-	0.9	1.4	V	V _{GS} =0V, I _{SD} =50A
Body Diode Reverse Recovery Time	t _{rr}	-	56	-	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	-	54	-	nC	IS=30A, VGS=0V, dIF/dt=100A/us;

※. Notes

2.Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.

3.Essentially independent of operating temperature.

Typical Performance Characteristics

Fig 1: Output Characteristics

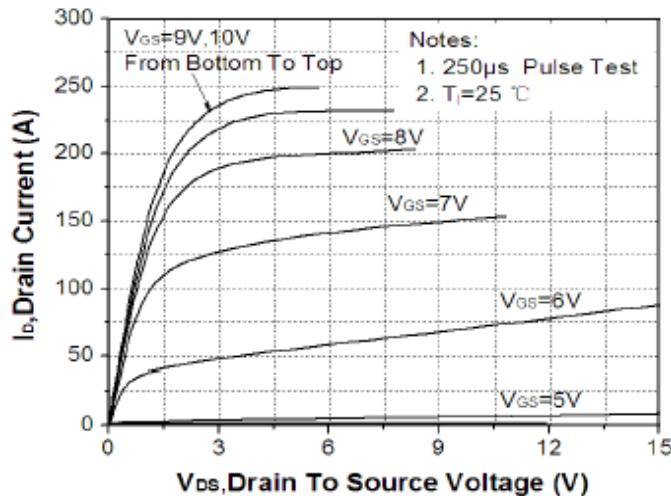


Fig 2: Transfer Characteristics

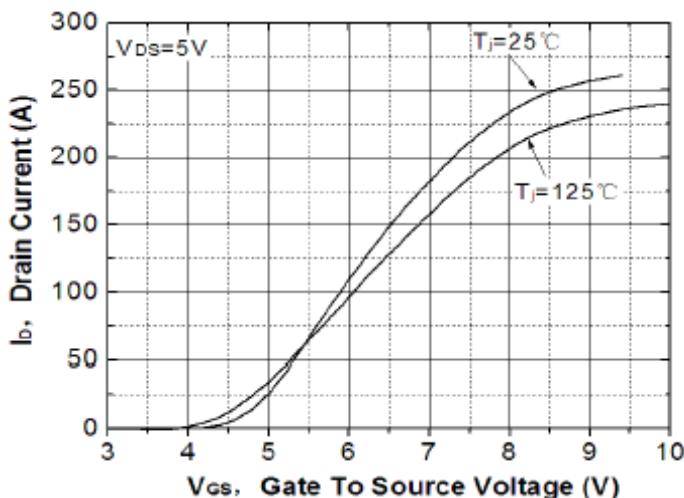
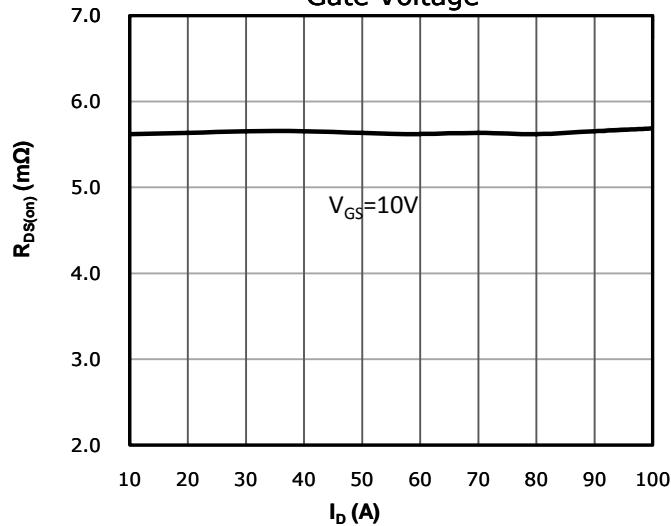
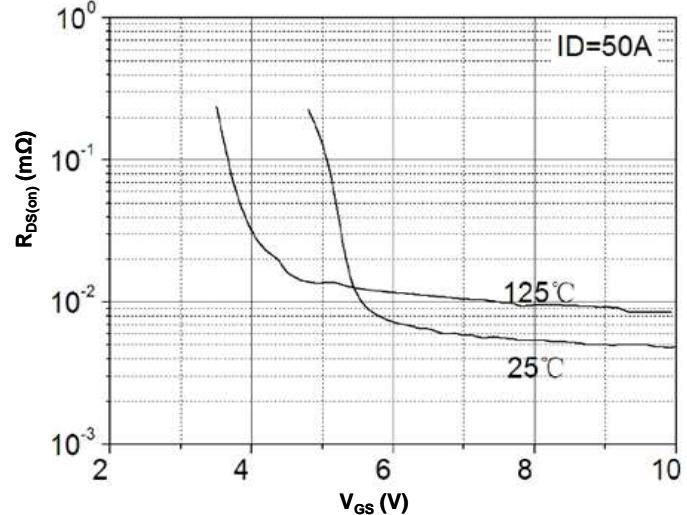
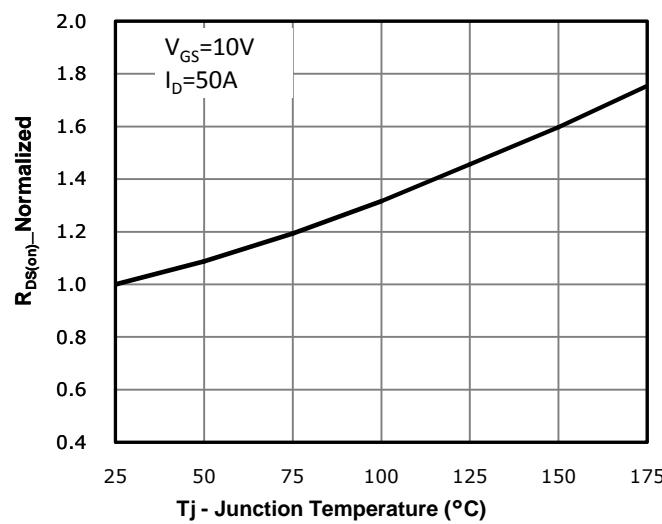

 Fig 3: $R_{DS(on)}$ vs Drain Current and Gate Voltage

 Fig 4: $R_{DS(on)}$ vs Gate Voltage

 Fig 5: $R_{DS(on)}$ vs. Temperature


Fig 6: Capacitance Characteristics

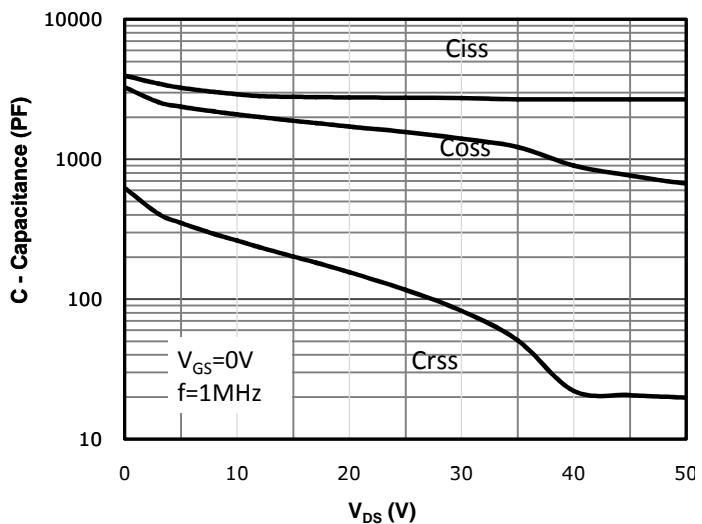


Fig 7: Gate Charge Characteristics

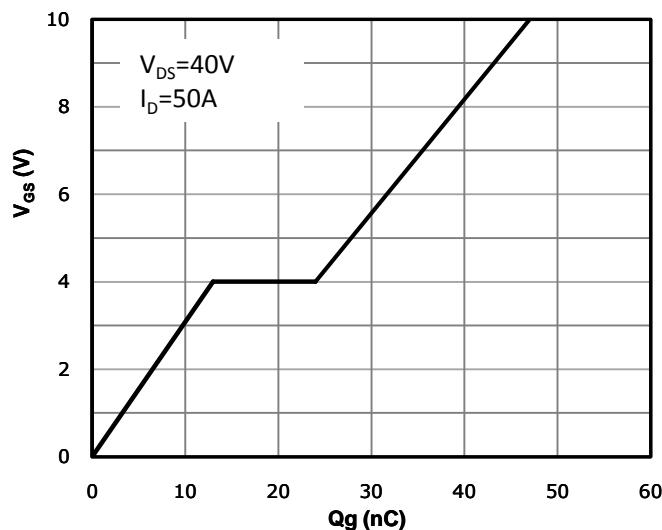


Fig 8: Body-diode Forward Characteristics

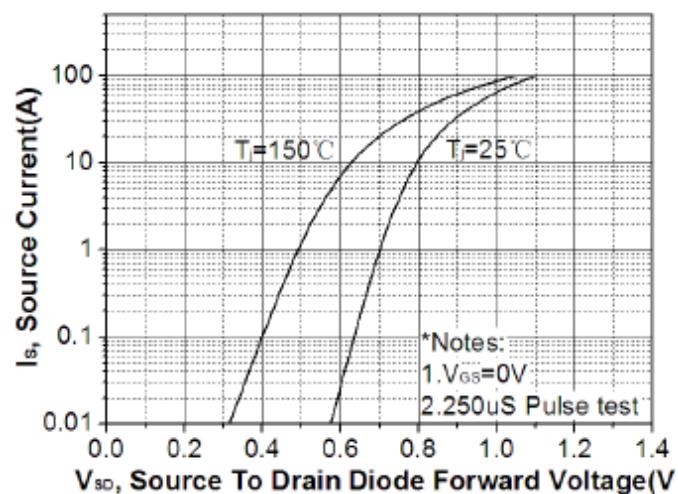


Fig 9: Power Dissipation

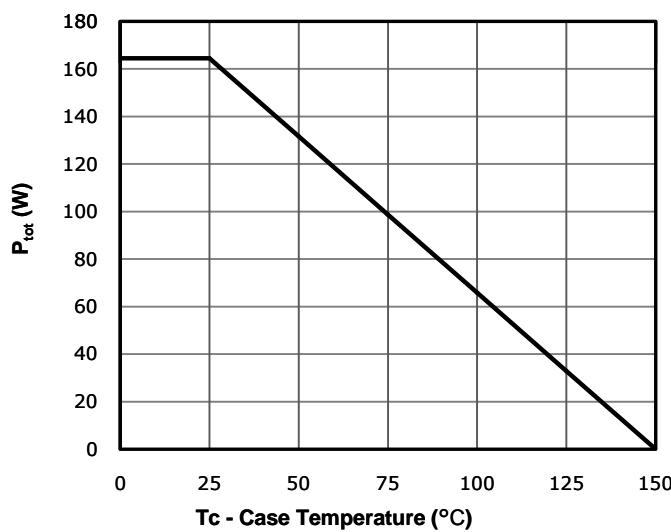


Fig 10: Drain Current Derating

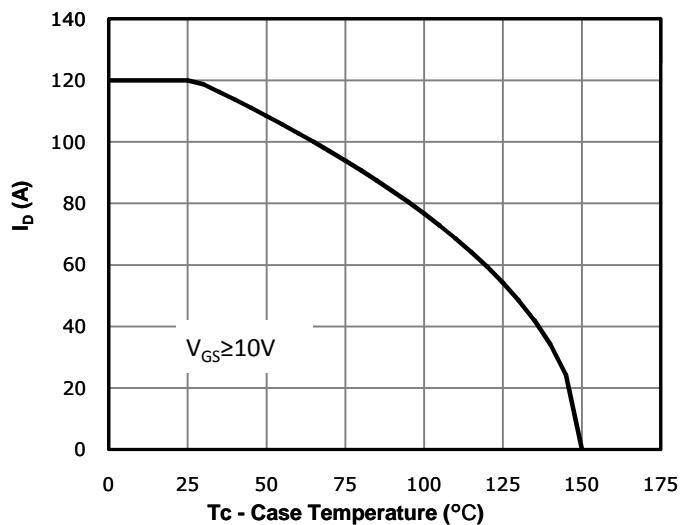


Fig 11: Safe Operating Area

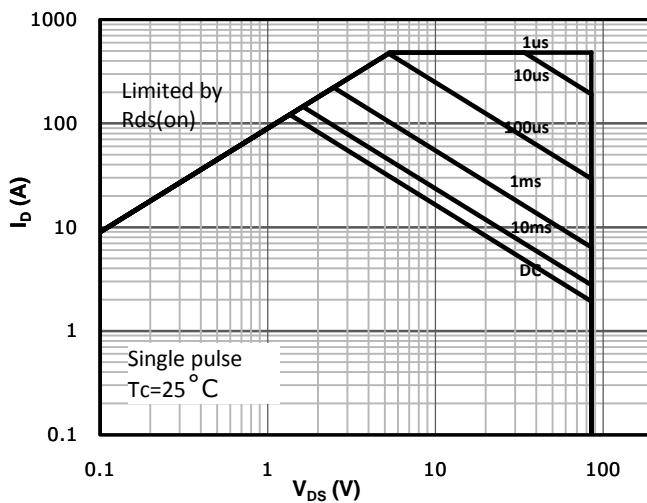
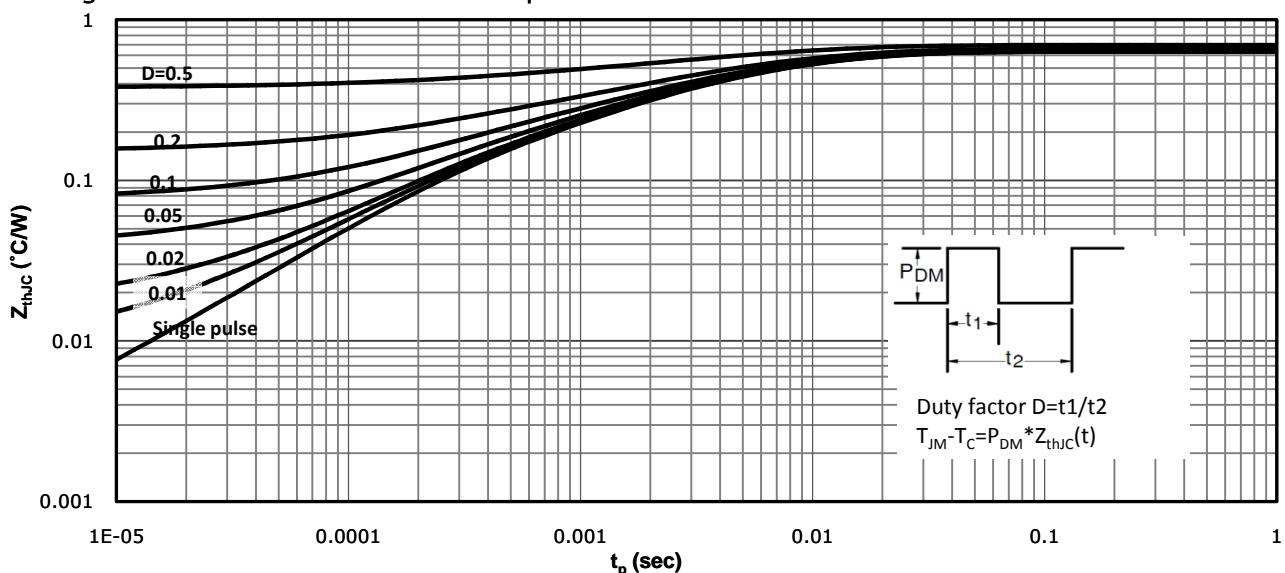
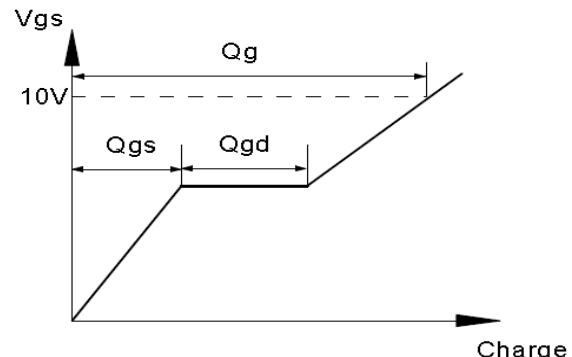
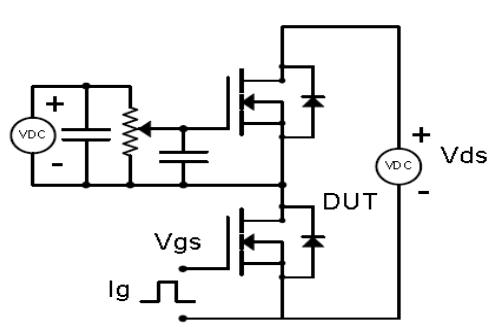


Fig 12: Max. Transient Thermal Impedance

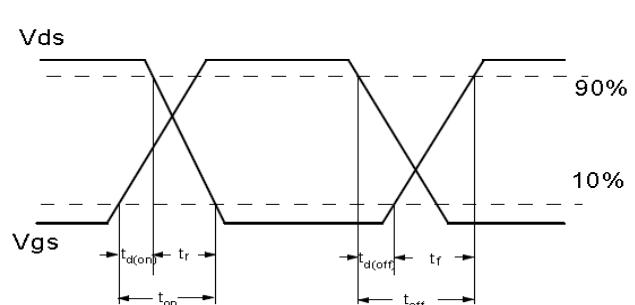
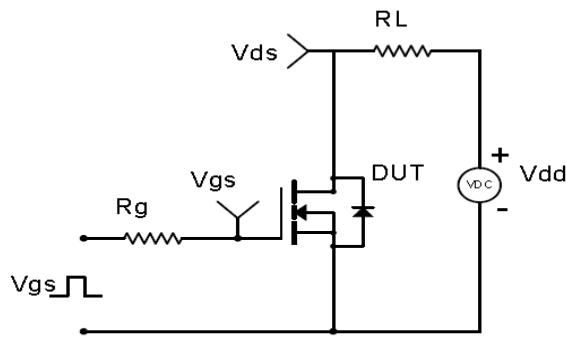


Test Circuit & Waveform

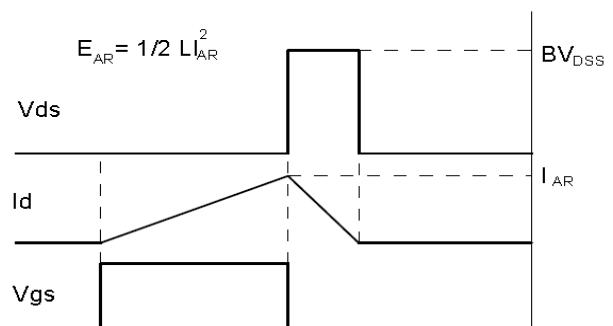
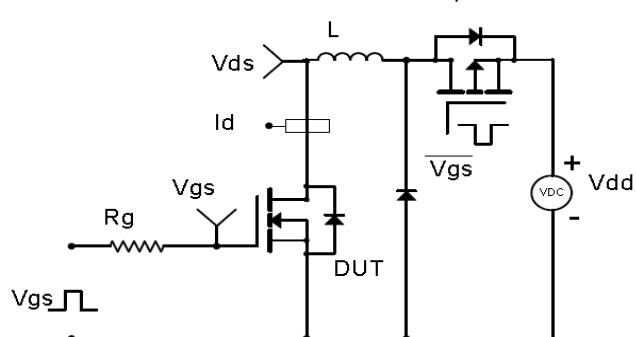
Gate Charge Test Circuit & Waveform



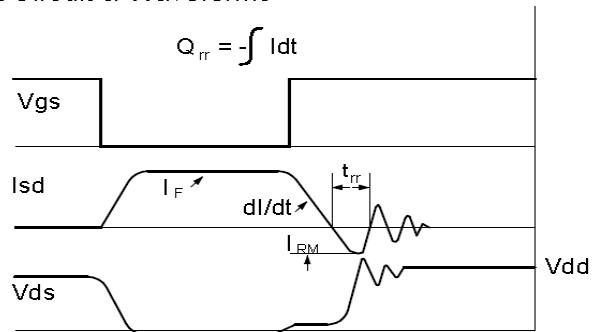
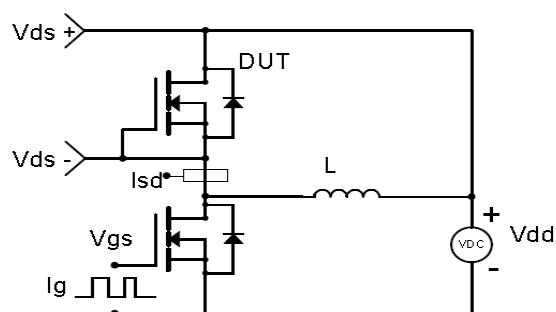
Resistive Switching Test Circuit & Waveforms

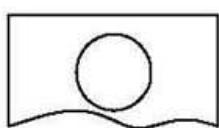
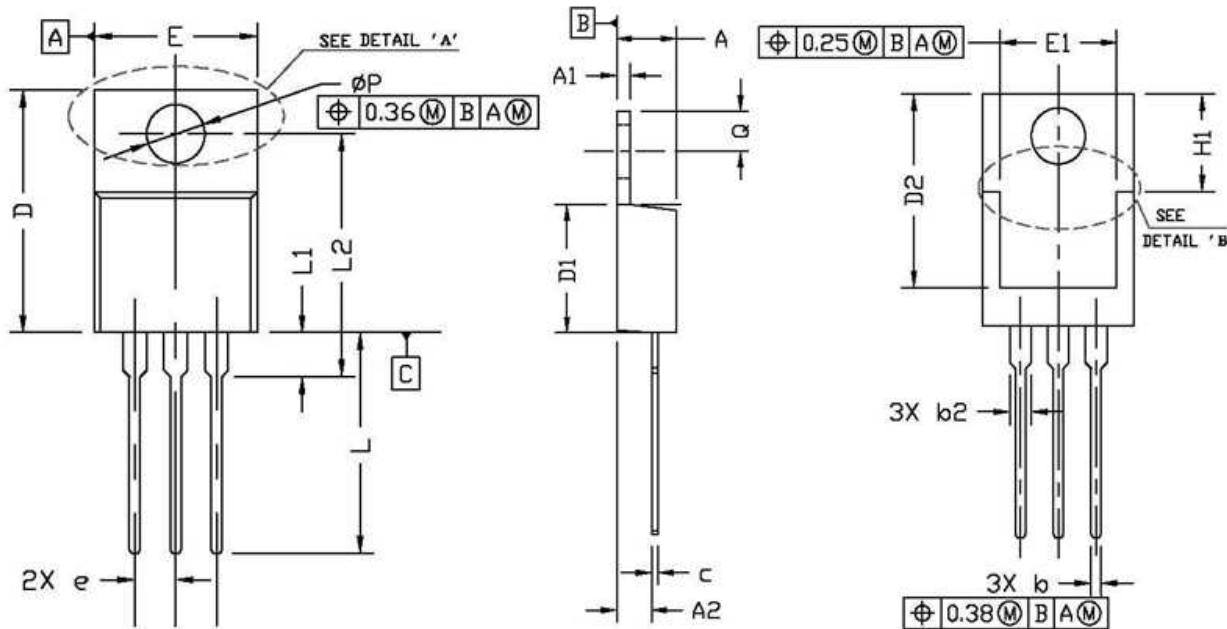


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

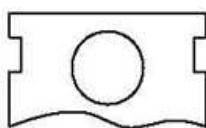


Diode Recovery Test Circuit & Waveforms

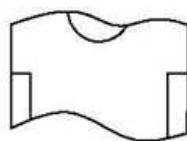


Package Outline: TO-220-3L


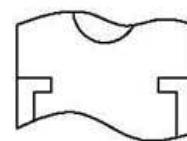
Option 1



Option 2



Option 1

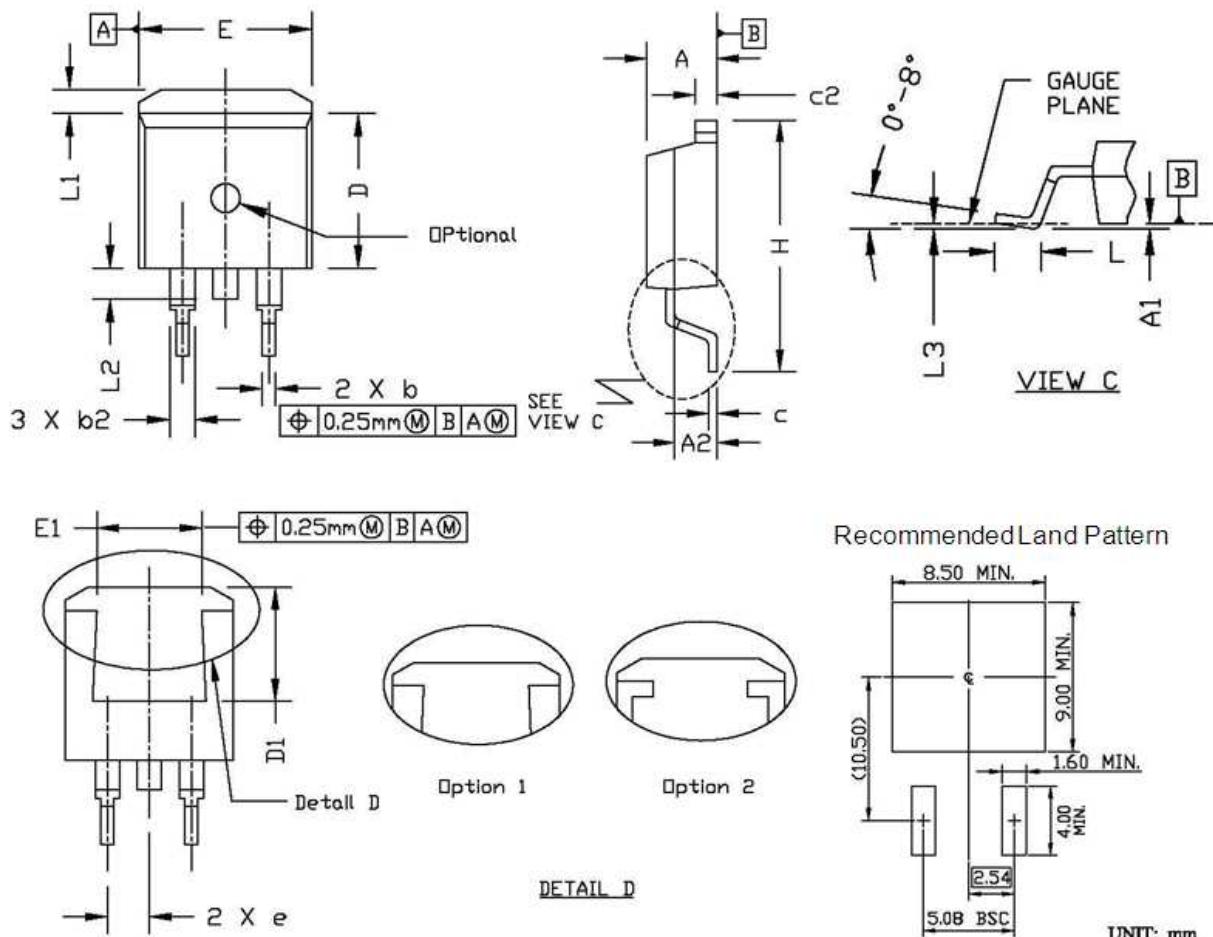


Option 2

Detail 'A'

Detail 'B'

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.80	0.169	0.189
A1	1.20	1.45	0.047	0.057
A2	2.20	2.90	0.087	0.114
b	0.69	0.95	0.027	0.037
b2	1.00	1.60	0.039	0.063
c	0.33	0.65	0.013	0.026
D	14.70	16.20	0.579	0.638
D1	8.59	9.65	0.338	0.380
D2	11.75	13.60	0.463	0.535
e	2.54 BSC.		0.100 BSC.	
E	9.60	10.60	0.378	0.417
E1	7.00	8.46	0.276	0.333
H1	6.20	7.00	0.244	0.276
L	12.60	14.80	0.496	0.583
L1	2.70	3.80	0.106	0.150
L2	12.13	16.50	0.478	0.650
Q	2.40	3.10	0.094	0.122
P	3.50	3.90	0.138	0.154

Package Outline: TO-263


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.86	0.169	0.191
A1	0.00	0.25	0.000	0.010
A2	2.34	2.79	0.092	0.110
b	0.68	0.94	0.027	0.037
b2	1.15	1.35	0.045	0.053
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.38	9.45	0.330	0.372
D1	6.90	8.17	0.272	0.322
e	2.54 BSC.		0.100 BSC.	
E	9.78	10.50	0.385	0.413
E1	6.50	8.60	0.256	0.339
H	14.61	15.88	0.575	0.625
L	2.24	3.00	0.088	0.118
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
L3	0.00	0.25	0.000	0.010



华润微电子(重庆)有限公司

SKST065N08N, SKSS063N08N

SkyMOS1 N-MOSFET 85V, 5.6mΩ, 105A

Revision History

Revison	Date	Major changes
1.2	2018-06-28	modify logo
2.0	2019-05-31	Supplement package outline info.

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

SkySilicon reserves the right to improve product design, function and reliability without notice.



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